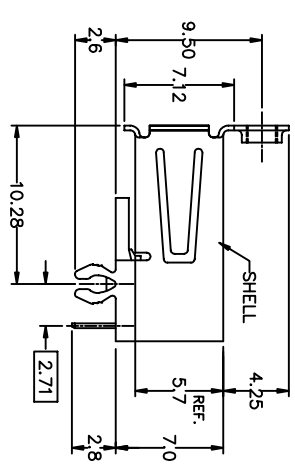
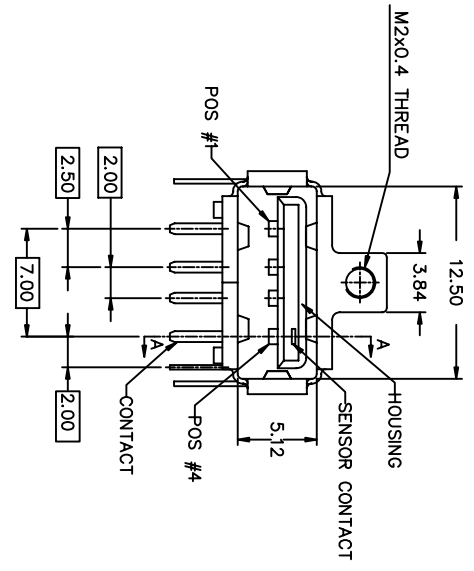
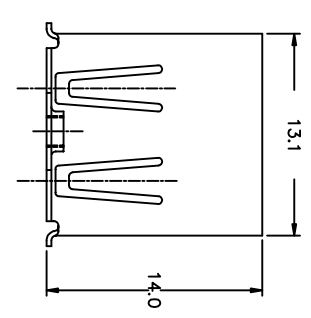
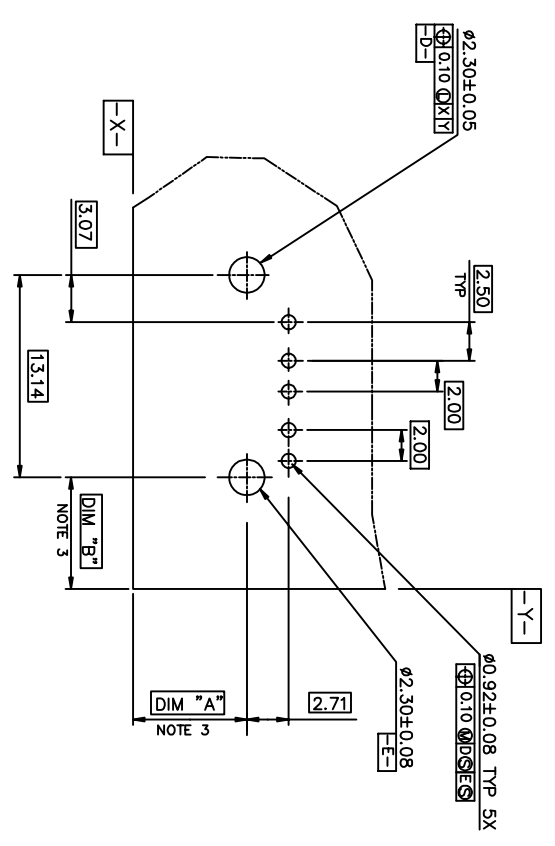


PRODUCT NO.
SEE SHEET 3



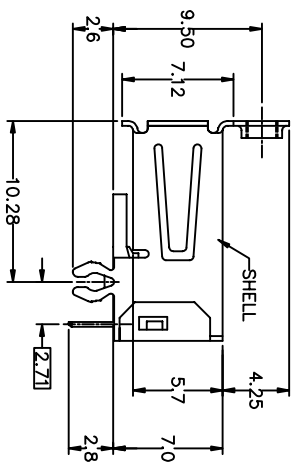
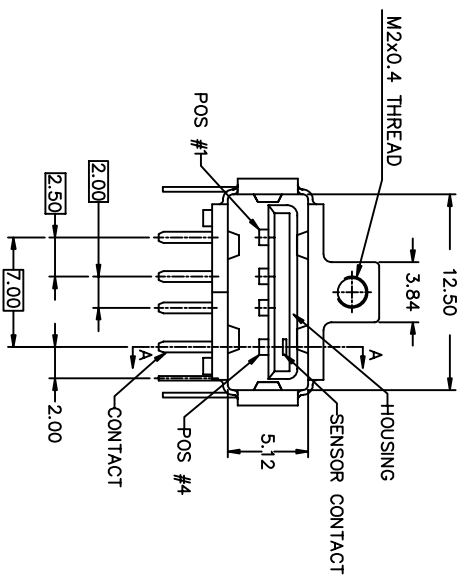
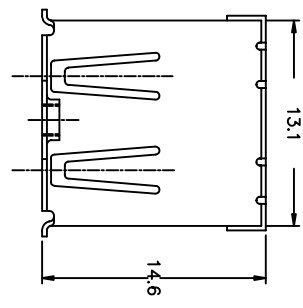
ASSEMBLY WITHOUT BACK SHIELD



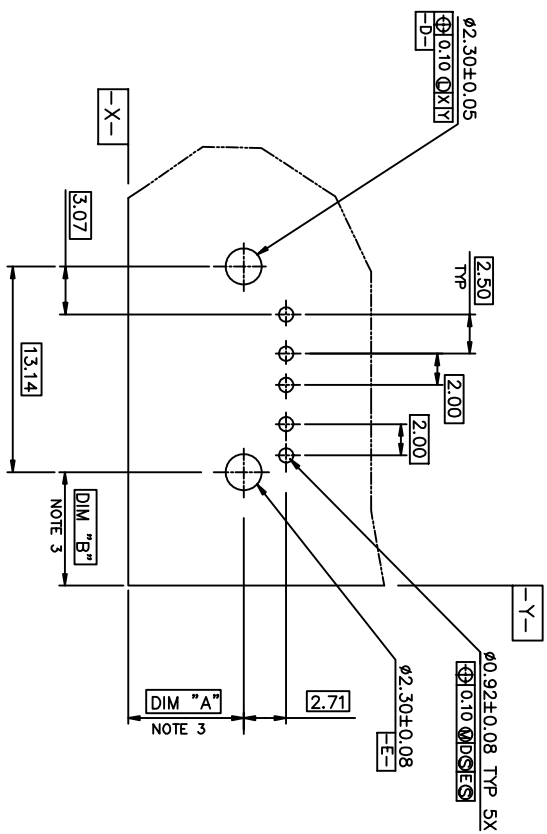
P.C. BOARD LAYOUT

rev.	ecn no.	dr.	date	tolerance unless otherwise specified	CUSTOMER COPY	title	sheet
A	T70233	P P	6/18/97	.00 ± 0.30	UNIVERSAL BUS	1	
B	T70333	C L	08/11/97	.0002 ± 0.10	RECEPTACLE-CATALOG	2	
C	T04-0208	W L	05/13/04	± .3	UNIVERSAL BUS	3	
D	N04-0123	PH	12/13/04		RECEPTACLE-CATALOG	4	
E	N06-0101	HB	04/13/08		RECEPTACLE-CATALOG	5	
sheet revision				projection		scale	
index sheet				chr		Z:S:1	
1				R Y LIU		01/10/97	
2				oppd JENN TSAO		01/10/97	
3							
4							
5							
6							

PRODUCT NO.
 SEE SHEET 3



ASSEMBLY WITH BACK SHIELD



P.C. BOARD LAYOUT

mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		title	
rev.	ecn no.	dr	date	linear	projection	UNIV. SERIAL BUS S.M.T.	code
B				.00 ± 0.20	AS	RECEPTACLE-CATALOG	
				.000 ± 0.10			
				± .3°			
				dir SHIPLEY HSD/01/10/97	unit mm/inch		
				engr R Y LIU 01/10/97	size		
				chr R Y LIU 01/10/97	scale		
				pppd JENN TSAO/01/10/97	2.5:1		
sheet	revision						sheet
index	sheet						2 OF

PRODUCT NUMBER CODE

61819 - X X X X X S LF

BASE PRODUCT NUMBER

HOUSING COLOR OPTIONS

- 0 - WHITE
- 1 - BLACK

PIN NO. OPTION

- 0 - 5 PIN
- 1 - 4 PIN

SHELL OPTIONS

- 1 - WITHOUT BACK SHIELD
- 2 - WITH BACK SHIELD

TERMINAL PLATING OPTION

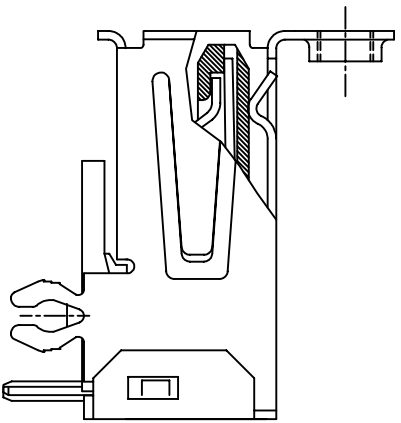
- 0 - 50u" Ni UNDERPLATE
- 30u" GXT CONTACT AREA
- 100u" TIN/LEAD TAIL AREA
- 1 - 50u" Ni UNDERPLATE
- 30u" GXT CONTACT AREA
- 100u" TIN TAIL AREA

PACKAGING OPTION

- B - TUBES

ONLY FOR PANASONIC

LEAD FREE OPTION
WHEN "TERMINAL PLATING OPTION" IS 1



NOTES:

1. MATERIAL: PHOSPHOR BRONZE
CONTACTS: PHOSPHOR BRONZE
SHIELD: PHOSPHOR BRONZE
HOUSING: UL 94V-0 THERMOPLASTIC, COLOR: WHITE
2. PLATING: CONTACTS: GOLD FLASH OVER
PALLADIUM NICKEL (0.76um MINIMUM) IN CONTACT
AREA; 2.54 um TIN-LEAD OR TIN MINIMUM IN SOLDER TAIL AREA.
1.27 um MINIMUM NICKEL UNDERPLATE OVER ALL SURFACES.
SHIELD: 2.54 um MINIMUM TIN/LEAD OR TIN OVER 1.27 um
MINIMUM NICKEL UNDERPLATE
3. DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER.
4. RECOMMENDED BOARD THICKNESS IS 0.8~1.2 mm.
5. MAXIMUM PANEL THICKNESS TO BE 2.67 mm IF MOUNTED
BEHIND PANEL.
6. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD
FREE P/N'S
7. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION
DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN
GS-22-008
8. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE
TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION,
INFRO-RED OR VAPOR PHASE REFLOW OVEN.

mat'l code	tolerance unless otherwise specified	CUSTOMER COPY	projection	title	product family	code
rev. econ no. dr.	date					
E	linear 0 ± 0.30 .00 ± 0.20 .000 ± 0.10			UNIVERSAL BUS RECEPTACLE	61819	3 OF
	angles ± .3°					
	dir Shirley HSJ/07/10/97					
	engr R Y LUU 07/10/97					
	chr R Y LUU 07/10/97					
	appd JENN TSAO/07/10/97					
sheet revision						
index sheet						